

	L #	Hits	Search Text	DBs
1	L1	369	photoconductive near switch\$3	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
2	L2	13	photoconductive near relay\$1	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
3	L3	373	1 or 2	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
4	L4	81176	bump\$1	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
5	L5	15	3 and 4	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B

	L #	Hits	Search Text	DBs
6	L6	248015	(ball\$1 or solder\$1 or metal\$1) same bond\$3	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
7	L7	27	3 and 6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
8	L8	13768	die near bond\$3	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
9	L9	6209	6 and 8	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
10	L10	680	9 and (switch\$3 or relay\$1)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B

	L #	Hits	Search Text	DBs
11	L11	640495	heat\$3 same pressur\$3	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TDB
12	L12	171	10 and 11	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TDB
13	L13	20325	flip near chip	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TDB
14	L14	9492	13 and 6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TDB
15	L15	1793	11 and 14	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TDB

	L #	Hits	Search Text	DBs
16	L16	303	15 and (switch\$3 or relay\$1)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TDB
17	L17	271132	257/\$.cccls.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TDB
18	L18	168	16 and 17	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TDB